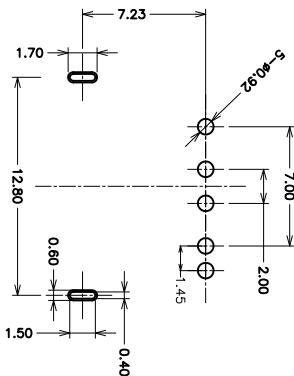
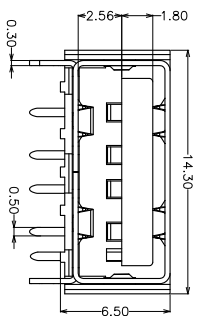
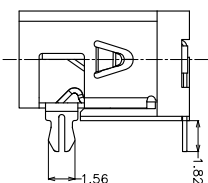
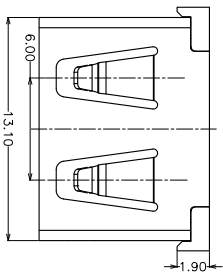
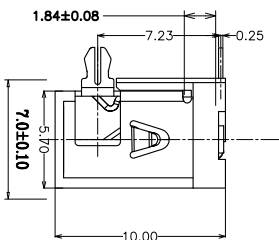
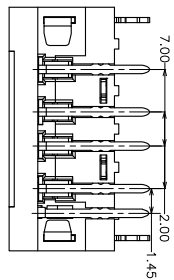
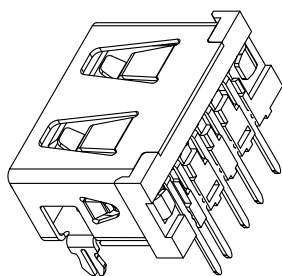


ROHS

1 2 3 4 7 8 9 10

MAPX	MODIFICATION	DRW	DATE



RECOMMEND P. C. B LAYOUT
TOLERANCE: ±0.10

NOTES:

- MATERIAL SPECIFICATION:
 - INSULATION MATERIAL: THERMOPLASTIC HALOGENFREE.
 - SHELL: COPPER ALLOY T: 0.30mm
PLATING: NICKEL
 - TERMINAL: COPPER ALLOY T: 0.25mm
PLATING: GOLD/TIN PLATED;
- ELECTRICAL CHARACTERISTIC:
 - INSULATION RESISTANCE: 1000MΩ MIN;
 - CONTACT RESISTANCE: 30mΩ MAX;
 - WITHSTANDING VOLTAGE: 500V AC;
- MECHANICAL CHARACTERISTICS:
 - INSERTION FORCE: 3.57kgf Max;
 - EXTRACTION FORCE: 1.02kgf Min;

产品图
PRODUCT CHART DWG

公差一览表
深圳市精拓金电子有限公司
Shenzhen Jing Tuo Jin Electronics Co., Ltd.

公差一览表	单位	MM	制图	许榕强	制图料号	
TOLERANCE UNLESS OTHERWISE	UNITS	MM	DRAWING	审核	PRODUCT PART NO.	
±0.35	X	±5.°	审核	郭治富	产品名称	USB A/F DIT90° 短体5P10.00mm
±0.20	X	±2.°	CHD	核准	PRODUCT NO.	
±0.15	XX	±1.°	日期	黄国荣	角法	
±0.05	XXX	±0.5°	DATE	2016-09-09	VER	版本
			APPD			A0

1 2 3 4 7 8 9 10

Autodesk 教育版产品制作

Autodesk 教育版产品制作